

# **Product Compliance Declaration**

Please see <a href="https://www.molex.com">www.molex.com</a> for the most up-to-date information.

## **Contact Information**

Name Molex Product Compliance E-Mail Product.Compliance@molex.com

## **Part Information**

Part Name STAC64 RAHDR 4BAY 50CKT 16B-16A-08A-10A

# **Product Composition**

Name	Туре	CAS Number	Proportion (% Total)	Mass (Grams)
STAC64 RAHDR 4BAY 50CKT 16B-16A-08A-10A	Assembly		100	31.244112
STAC64 RA HDR 16 CKT GRY POL B TRAY	Assembly		24.1133	7.534
STAC64 RA HDR HOUSING 16 CKT GRY POL B	Component		18.2242	5.694
PS-ST GF30	Material		18.2242	5.694
PS-ST	Substance		10.6953	3.341666
GF-Fibre	Substance		5.4445	1.701082
Pigment portion, not to declare	Substance	system	0.2232	0.069752
Benzene, ethenyl-, polymer with 1,3-butadiene, hydrogenated	Substance	66070-58-4	1.2404	0.387551
Further Additives, not to declare	Substance	system	0.6208	0.193949
0.64 X 34.93 SQ PIN BRASS REFLOW SN	Component		3.2006	1
SQ WIRE C26000 PL 0.625 X 0.625	Material		3.2006	1
Cartridge Brass 70% Unplated	Material		3.1349	0.97946
Copper	Substance	7440-50-8	2.1944	0.685622

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Name	Туре	CAS Number	Proportion (% Total)	Mass (Grams)
Zinc (metal)	Substance	7440-66-6	0.9405	0.293838
Copper Plating	Material		0.0063	0.001962
Copper	Substance	7440-50-8	0.0063	0.001962
Tin Plating	Material		0.0343	0.010729
Tin	Substance	7440-31-5	0.0343	0.010729
Nickel Plating	Material		0.0251	0.007849
Nickel	Substance	7440-02-0	0.0251	0.007848
Further Additives, not to declare	Substance	system	3E-06	8E-07
0.64 X 29.86 SQ PIN BRASS REFLOW SN	Component		2.5349	0.792
SQ WIRE C26000 PL 0.625 X 0.625	Material		2.5349	0.792
Cartridge Brass 70% Unplated	Material		2.4828	0.775732
Copper	Substance	7440-50-8	1.738	0.543013
Zinc (metal)	Substance	7440-66-6	0.7448	0.23272
Copper Plating	Material		0.005	0.001554
Copper	Substance	7440-50-8	0.005	0.001554
Tin Plating	Material		0.0272	0.008497
Tin	Substance	7440-31-5	0.0272	0.008497
Nickel Plating	Material		0.0199	0.006216
Nickel	Substance	7440-02-0	0.0199	0.006216
Further Additives, not to declare	Substance	system	2E-06	6E-07
PIN ALIGNMENT PLATE-16CKT STAC64	Component		0.1536	0.048
PET ST MYLAR 0.25 X 26.86	Material		0.1536	0.048
Polyethylene terephthalate	Substance	25038-59-9	0.1495	0.046704
Further Additives, not to declare	Substance	system	0.0041	0.001296
STAC64 RA HDR 16 CKT BLK POL A TRAY	Assembly		24.1133	7.534
STAC64 RA HDR HOUSING 16 CKT BLK POL A	Component		18.2242	5.694
PS-ST GF30 Black	Material		18.2242	5.694
PS-ST	Substance		10.6503	3.327596
GF-Fibre	Substance		5.4994	1.718233

Name	Туре	CAS Number	Proportion (% Total)	Mass (Grams)
Pigment portion, not to declare	Substance	system	0.1209	0.037763
Further Additives, not to declare	Substance	system	0.5628	0.175836
Benzene, ethenyl-, polymer with 1,3-butadiene, hydrogenated	Substance	66070-58-4	1.3909	0.434572
0.64 X 34.93 SQ PIN BRASS REFLOW SN	Component		3.2006	1
SQ WIRE C26000 PL 0.625 X 0.625	Material		3.2006	1
Cartridge Brass 70% Unplated	Material		3.1349	0.97946
Copper	Substance	7440-50-8	2.1944	0.685622
Zinc (metal)	Substance	7440-66-6	0.9405	0.293838
Copper Plating	Material		0.0063	0.001962
Copper	Substance	7440-50-8	0.0063	0.001962
Tin Plating	Material		0.0343	0.010729
Tin	Substance	7440-31-5	0.0343	0.010729
Nickel Plating	Material		0.0251	0.007849
Nickel	Substance	7440-02-0	0.0251	0.007848
Further Additives, not to declare	Substance	system	3E-06	8E-07
0.64 X 29.86 SQ PIN BRASS REFLOW SN	Component		2.5349	0.792
SQ WIRE C26000 PL 0.625 X 0.625	Material		2.5349	0.792
Cartridge Brass 70% Unplated	Material		2.4828	0.775732
Copper	Substance	7440-50-8	1.738	0.543013
Zinc (metal)	Substance	7440-66-6	0.7448	0.23272
Copper Plating	Material		0.005	0.001554
Copper	Substance	7440-50-8	0.005	0.001554
Tin Plating	Material		0.0272	0.008497
Tin	Substance	7440-31-5	0.0272	0.008497
Nickel Plating	Material		0.0199	0.006216
Nickel	Substance	7440-02-0	0.0199	0.006216
Further Additives, not to declare	Substance	system	2E-06	6E-07
PIN ALIGNMENT PLATE-16CKT STAC64	Component		0.1536	0.048
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Name	Туре	CAS Number	Proportion (% Total)	Mass (Grams)
PET ST MYLAR 0.25 X 26.86	Material		0.1536	0.048
Polyethylene terephthalate	Substance	25038-59-9	0.1495	0.046704
Further Additives, not to declare	Substance	system	0.0041	0.001296
STAC64 RA HDR 8 CKT BLK POL A TRAY	Assembly		16.5535	5.172
STAC64 RA HDR HOUSING 8 CKT BLK POL A	Component		13.5001	4.218
PS-ST GF30 Black	Material		13.5001	4.218
PS-ST	Substance		7.8895	2.465016
GF-Fibre	Substance		4.0738	1.272832
Pigment portion, not to declare	Substance	system	0.0895	0.027974
Further Additives, not to declare	Substance	system	0.4169	0.130256
Benzene, ethenyl-, polymer with 1,3-butadiene, hydrogenated	Substance	66070-58-4	1.0303	0.321922
0.64 X 34.93 SQ PIN BRASS REFLOW SN	Component		1.6003	0.5
SQ WIRE C26000 PL 0.625 X 0.625	Material		1.6003	0.5
Cartridge Brass 70% Unplated	Material		1.5674	0.48973
Copper	Substance	7440-50-8	1.0972	0.342811
Zinc (metal)	Substance	7440-66-6	0.4702	0.146919
Copper Plating	Material		0.0031	0.000981
Copper	Substance	7440-50-8	0.0031	0.000981
Tin Plating	Material		0.0172	0.005365
Tin	Substance	7440-31-5	0.0172	0.005365
Nickel Plating	Material		0.0126	0.003925
Nickel	Substance	7440-02-0	0.0126	0.003924
Further Additives, not to declare	Substance	system	1E-06	4E-07
0.64 X 29.86 SQ PIN BRASS REFLOW SN	Component		1.2674	0.396
SQ WIRE C26000 PL 0.625 X 0.625	Material		1.2674	0.396
Cartridge Brass 70% Unplated	Material		1.2414	0.387866
Copper	Substance	7440-50-8	0.869	0.271506
Zinc (metal)	Substance	7440-66-6	0.3724	0.11636
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Name	Туре	CAS Number	Proportion (% Total)	Mass (Grams)
Copper Plating	Material		0.0025	0.000777
Copper	Substance	7440-50-8	0.0025	0.000777
Tin Plating	Material		0.0136	0.004249
Tin	Substance	7440-31-5	0.0136	0.004249
Nickel Plating	Material		0.0099	0.003108
Nickel	Substance	7440-02-0	0.0099	0.003108
Further Additives, not to declare	Substance	system	1E-06	3E-07
PIN ALIGNMENT PLATE-8CKT STAC64	Component		0.1856	0.058
ST MYLAR 0.25 X 16.70 PET NATURAL	Material		0.1856	0.058
PET	Material		0.1856	0.058
Polyethylene terephthalate	Substance	25038-59-9	0.1806	0.056434
Further Additives, not to declare	Substance	system	0.005	0.001566
POWERSTAC RAHDR 10 CKT BLK POL A TRAY	Assembly		35.2198	11.004112
POWERSTAC RAHDR HOUSING 10 CKT BLK POL A	Component		21.1816	6.618
PS-ST GF30 Black	Material		21.1816	6.618
PS-ST	Substance		12.3786	3.867586
GF-Fibre	Substance		6.3918	1.997061
Pigment portion, not to declare	Substance	system	0.1405	0.043891
Further Additives, not to declare	Substance	system	0.6541	0.20437
Benzene, ethenyl-, polymer with 1,3-butadiene, hydrogenated	Substance	66070-58-4	1.6166	0.505092
1.50 X 36.44 SOLDERTAIL BLADE REFLOW SN	Component		7.0481	2.202112
HSM Copper Unplated	Material		6.9901	2.184
Copper	Substance	7440-50-8	6.8105	2.12788
Iron	Substance	7439-89-6	0.1648	0.051492
Phosphorus	Substance	7723-14-0	0.0059	0.001848
Zinc (metal)	Substance	7440-66-6	0.0089	0.00278
Nickel Plating	Material		0.0176	0.005512
Nickel	Substance	7440-02-0	0.0176	0.005512
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Name	Туре	CAS Number	Proportion (% Total)	Mass (Grams)
Further Additives, not to declare	Substance	system	2E-06	6E-07
Tin Plating	Material		0.0403	0.0126
Tin	Substance	7440-31-5	0.0403	0.0126
2.80 X 27.49 DUAL TAIL BLADE REFLOW SN	Component		6.6701	2.084
HSM Copper Unplated	Material		6.6188	2.068
Copper	Substance	7440-50-8	6.4488	2.014861
Iron	Substance	7439-89-6	0.1561	0.048757
Phosphorus	Substance	7723-14-0	0.0056	0.00175
Zinc (metal)	Substance	7440-66-6	0.0084	0.002633
Nickel Plating	Material		0.0166	0.0052
Nickel	Substance	7440-02-0	0.0166	0.005199
Further Additives, not to declare	Substance	system	2E-06	5E-07
Tin Plating	Material		0.0346	0.0108
Tin	Substance	7440-31-5	0.0346	0.0108
PIN ALIGNMENT PLATE-10CKT POWRSTAC	Component		0.3201	0.1
PET ST MYLAR 0.25 X 31.94	Material		0.3201	0.1
Polyethylene terephthalate	Substance	25038-59-9	0.3114	0.0973
Further Additives, not to declare	Substance	system	0.0086	0.0027

# **ROHS Declaration Information**

Regulatory Revision EU 2015/863

Compliance Status Compliant

**Contained Substances Exceeding Threshold** 

None

**Exemptions** 

None

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# **REACH-SVHC Declaration Information**

Regulatory Revision D(2020)9139-DC (19 Jan 2021)

# **Contained Substances Exceeding Threshold**

None

## **GADSL Declaration Information**

Regulatory Revision GADSL imported from IMDS

# **Contained Substances Exceeding Threshold**

Substance Group	Substance Location	Threshold (PPM)	Concentration (PPM)	Intentionally Added
lead	High Copper Alloy	*Note	138.02	Yes
lead	e-plate Sn (electrodeposited Tin Coatings, bright and matt)	*Note	150	Yes
styrene	PS-ST GF30 Black	*Note	700	Yes
nickel powder [particle diameter < 1 mm]	Ep-Ni	*Note	997,500	Yes
copper	High Copper Alloy	*Note	974,600.55	Yes
copper	e-plate Cu (electrodeposited Copper Coatings)	*Note	999,625	Yes
glass, oxide, chemicals	PS-ST GF30 Black	*Note	300,000	Yes
glass, oxide, chemicals	PS-ST GF30	*Note	320,000	Yes
lead	Cartridge Brass 70% (CA260)	*Note	350	Yes
copper	Cartridge Brass 70% (CA260)	*Note	700,000	Yes

<sup>\*</sup>Note: For GADSL substance declarable/prohibited threshold values, please reference http://www.gadsl.org/

## **Exemptions**

Part Name	ne Exemption		
High Copper Alloy	44 Concentration within acceptable GADSL limits		
e-plate Sn (electrodeposited Tin Coatings, bright and matt)	44 Concentration within acceptable GADSL limits		
Ep-Ni	33 Other application (Surface not routinely touched or nickel release rate < 0.5µg/cm2/week)		
Cartridge Brass 70% (CA260)	44 Concentration within acceptable GADSL limits		

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# **HFLH Declaration Information**

Regulatory Revision IEC 61249-2-21

# **Contained Substances Exceeding Threshold**

None

# **China ROHS Declaration Information**

Part Number 0347084011

Part Name STAC64 RAHDR 4BAY 50CKT

16B-16A-08A-10A

#### Part Information



art information	Hazardous Substances					
Components	Lead	Mercury	Cadmium	Hex. Chromium	PBB	PBDE
STAC64 RAHDR 4BAY 50CKT 16B-16A-08A-10A	0	0	0	0	0	0
STAC64 RA HDR 16 CKT GRY POL B TRAY	0	0	0	0	0	0
STAC64 RA HDR HOUSING 16 CKT GRY POL B	0	0	0	0	0	0
0.64 X 34.93 SQ PIN BRASS REFLOW SN	0	0	0	0	0	0
0.64 X 29.86 SQ PIN BRASS REFLOW SN	0	0	0	0	0	0
PIN ALIGNMENT PLATE-16CKT STAC64	0	0	0	0	0	0
STAC64 RA HDR 16 CKT BLK POL A TRAY	0	0	0	0	0	0
STAC64 RA HDR HOUSING 16 CKT BLK POL A	0	0	0	0	0	0
0.64 X 34.93 SQ PIN BRASS REFLOW SN	0	0	0	0	0	0
0.64 X 29.86 SQ PIN BRASS REFLOW SN	0	0	0	0	0	0
PIN ALIGNMENT PLATE-16CKT STAC64	0	0	0	0	0	0
STAC64 RA HDR 8 CKT BLK POL A TRAY	0	0	0	0	0	0
STAC64 RA HDR HOUSING 8 CKT BLK POL A	0	0	0	0	0	0
0.64 X 34.93 SQ PIN BRASS REFLOW SN	0	0	0	0	0	0
0.64 X 29.86 SQ PIN BRASS REFLOW SN	0	0	0	0	0	0
PIN ALIGNMENT PLATE-8CKT STAC64	0	0	0	0	0	0
POWERSTAC RAHDR 10 CKT BLK POL A TRAY	0	0	0	0	0	0
POWERSTAC RAHDR HOUSING 10 CKT BLK POL A	0	0	0	0	0	0

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Components	Lead	Mercury	Cadmium	Hex. Chromium	PBB	PBDE
1.50 X 36.44 SOLDERTAIL BLADE REFLOW SN	0	0	0	0	0	0
2.80 X 27.49 DUAL TAIL BLADE REFLOW SN	0	0	0	0	0	0
PIN ALIGNMENT PLATE-10CKT POWRSTAC	0	0	0	0	0	0

## **Process Information**

Component Plating / Surface Finish	MSn-RNi
Termination Base Alloy	Brass
Solder Alloy	N/A
Process Capability	WAVE
Maximum Exposure Time (seconds)	040
Maximum Process Temperature (C)	260
Maximum Cycles at Reflow Temperature	003
J-STD-020 Moisture Sensitivity Level	N/A

Mar 24, 2021